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INVENTOR-Verhaverbeke, Steven and Truman, J. Kelly

ABSTRACT:

The present invention is a novel cleaning method and a solution for use in a single wafer cleaning process. According to the present invention the cleaning solution comprises ammonium hydroxide (NH.sub.4OH), hydrogen peroxide (H.sub.2O.sub.2), water (H.sub.2O) and a chelating agent. In an embodiment of the present invention the cleaning solution also contains a surfactant. And still yet another embodiment of the present invention the cleaning solution also comprises a dissolved gas such as H.sub.2. In a particular embodiment of the present invention, this solution is used by spraying or dispensing it on a spinning wafer.

SEARCH: claims 20 and 21 for "polyoxyethylene butylphenyl ether" and "polyoxyethylene alkylphenyl sulfate" in "cleaning" a "wafer" or "semiconductor"

- 1. A method of processing a wafer comprising: placing a wafer in a single wafer cleaning tool; spinning said wafer in said single wafer cleaning tool and while spinning said wafer; after placing said wafer in said single wafer cleaning tool, exposing said wafer to a solution comprising: NH.sub.40H; H.sub.20; and a chelating agent.
- 15. The method of claim 1 wherein said solution is further comprises a surfactant.

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